

EAST Search History**EAST Search History (Prior Art)**

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1248	438/455.ccls. and @ad< "20041029"	US_PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/07/01 07:56
L2	297	438/456.ccls. and @ad< "20041029"	US_PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/07/01 07:56
L3	1368	(257/704).ccls. and @ad< "20041029"	US_PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/07/01 07:56
L4	1712	(257/E21.211).ccls. and @ad< "20041029"	US_PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/07/01 07:56
L5	1464	(257/E23.193).ccls. and @ad< "20041029"	US_PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/07/01 07:56
L6	17	(L1 or L2 or L3 or L4 or L5) and @pd> "20091201"	US_PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/07/01 07:57

L11	50	(US-20040259325-\$ or US-20040142540-\$ or US-20060033213-\$ or US-20050056923-\$ or US-20060162956-\$ or US-20050121806-\$ or US-20040164649-\$ or US-20030111742-\$ or US-20040214406-\$ or US-20040253798-\$ or US-20060043483-\$ or US-20040224481-\$ or US-20040219762-\$ or US-20030189231-\$ or US-20030170936-\$ or US-20080238264-\$ or US-20080268382-\$ or US-20040067604-\$ or US-20060001123-\$ or US-20040080469-\$ or US-20040080261-\$ or US-20040066258-\$ or US-20030107096-\$ or US-20050122030-\$ or US-20030227663-\$).did. or (US-5591679-\$ or US-6555414-\$ or US-6326683-\$ or US-6326241-\$ or US-6774010-\$ or US-6355501-\$ or US-6069099-\$ or US-6238829-\$ or US-5955771-\$ or US-5772486-\$ or US-5352482-\$ or US-5122930-\$ or US-5094969-\$ or US-5006923-\$ or US-7008855-\$ or US-6448109-\$ or US-6074891-\$ or US-5604160-\$ or US-4528613-\$ or US-4122232-\$ or US-6879096-\$ or US-6525468-\$ or US-5545912-\$ or US-6514789-\$ or US-4943470-\$).did.	US-PGPUB; USPAT	OR	ON	2010/07/01 12:40
L13	31	L11 and (melt\$3 or premelt\$3 or pre-melt\$3)	US-PGPUB; USPAT	OR	ON	2010/07/01 12:40

L14	17	L11 and ((melt\$3 or premelt\$3 or pre-melt\$3) with (glass or frit or paste))	US-PGPUB; USPAT	OR	ON	2010/07/01 12:44
L16	5	((pre melt\$3 or pre-melt \$3) near8 (glass adj (frit or paste))) and @ad<"20031029"	US-PGPUB; USPAT	OR	ON	2010/07/01 13:34
L17	7	((pre melt\$3 or pre-melt \$3) with (glass adj (frit or paste))) and @ad<"20031029"	US-PGPUB; USPAT	OR	ON	2010/07/01 13:37
L18	88	((dry or drying or dried) near8 (temperature or degree) near8 (glass adj (frit or paste))) and @ad<"20031029"	US-PGPUB; USPAT	OR	ON	2010/07/01 13:48
L19	17	((glass adj (frit or paste)) with (prebak\$3 or pre-bak \$3)) and @ad<"20031029"	US-PGPUB; USPAT	OR	ON	2010/07/01 13:57
S54	2	"6069099".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/06/22 13:55
S56	2	US-20080268382-\$ did.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/06/22 14:01
S57	77	(conduct\$3 near4 (glass near3 (paste or frit))) and ((nonconduct\$3 or non-conduct\$3 or insulat\$3) near4 (glass near3 (paste or frit))) and ((wafer or substrate) near5 (bond\$3 or join\$3)) and @ad<"20041029"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/06/22 14:06
S58	9	("4417392" "4640010" "4682414" "4899118" "4967201").PN. OR ("5094969").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2010/06/22 14:53
S59	2638	438/455-459.ccls. and @ad<"20041029"	US-PGPUB; USPAT; USOCR	OR	ON	2010/06/22 14:57

S60	82	S59 and (glass near3 (paste or frit))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/06/22 14:57
S62	502	((wafers! or substrates!) near5 bond\$3) and (glass near3 (paste or frit)) and (conduct\$3) and (nonconduct\$3 or non-conduct\$3 or insulat\$3) and @ad<"20041029"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/06/23 12:59
S63	21	((wafers! or substrates!) near5 bond\$3) and ((glass near3 (paste or frit)) with (conduct\$3)) and ((glass near3 (paste or frit)) with (nonconduct\$3 or non-conduct\$3 or insulat\$3)) and @ad<"20041029"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/06/23 13:05
S65	32	((device or MEMS or system) near3 (wafer or substrate)) and ((cap or capping or cover or covering) near3 (wafer or substrate)) and ((glass near3 (paste or frit)) with (conduct\$3)) and ((glass near3 (paste or frit)) with (nonconduct\$3 or non-conduct\$3 or insulat\$3)) and @ad<"20041029"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/06/23 14:07
S66	20	((semiconduct\$3 or silicon) near3 (wafer or substrate)) and ((cap or capping or cover or covering) near3 (wafer or substrate)) and ((glass near3 (paste or frit)) with (conduct\$3)) and ((glass near3 (paste or frit)) with (nonconduct\$3 or non-conduct\$3 or insulat\$3)) and @ad<"20041029"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/06/23 14:52
S67	28	("5089876" "5115291" "5146389" "5216490" "5381300").PN. OR ("5545912").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2010/06/23 15:05
S68	16	S67 and (glass or frit)	US-PGPUB; USPAT; USOCR	OR	ON	2010/06/23 15:06

EAST Search History (Interference)

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7/1/2010 2:23:47 PM

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